

**SURFACE MOUNT SCHOTTKY BARRIER DIODE ARRAY**
**Features**

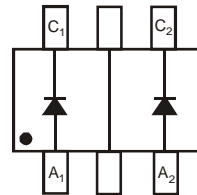
- Low Forward Voltage Drop
- Fast Switching
- Ultra-Small Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- **Lead Free/RoHS Compliant (Note 3)**
- **"Green" Device (Note 4 and 5)**



Top View

**Mechanical Data**

- Case: SOT-363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Orientation: See Diagram
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.006 grams (approximate)


 (Jumper  
connection  
between  
middle pins)

**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	30	V
Forward Continuous Current (Note 1)	I <sub>F</sub>	200	mA
Repetitive Peak Forward Current (Note 1)	I <sub>FRM</sub>	300	mA
Forward Surge Current (Note 1) @ t < 1.0s	I <sub>FSM</sub>	600	mA

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	P <sub>D</sub>	200	mW
Thermal Resistance, Junction to Ambient Air (Note 1)	R <sub>θJA</sub>	625	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +125	°C

**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	V <sub>(BR)R</sub>	30	—	—	V	I <sub>R</sub> = 100μA
Forward Voltage	V <sub>F</sub>	—	—	240 320 400 500 1000	mV	I <sub>F</sub> = 0.1mA I <sub>F</sub> = 1mA I <sub>F</sub> = 10mA I <sub>F</sub> = 30mA I <sub>F</sub> = 100mA
Reverse Leakage Current (Note 2)	I <sub>R</sub>	—	—	2.0	μA	V <sub>R</sub> = 25V
Total Capacitance	C <sub>T</sub>	—	—	10	pF	V <sub>R</sub> = 1.0V, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	—	5.0	ns	I <sub>F</sub> = 10mA through I <sub>R</sub> = 10mA to I <sub>R</sub> = 1.0mA, R <sub>L</sub> = 100Ω

- Notes:
1. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  2. Short duration pulse test used to minimize self-heating effect.
  3. No purposefully added lead.
  4. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  5. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

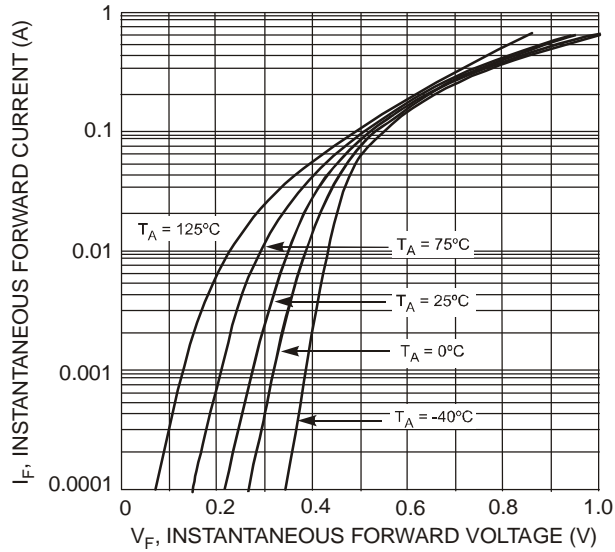


Fig. 1 Typical Forward Characteristics

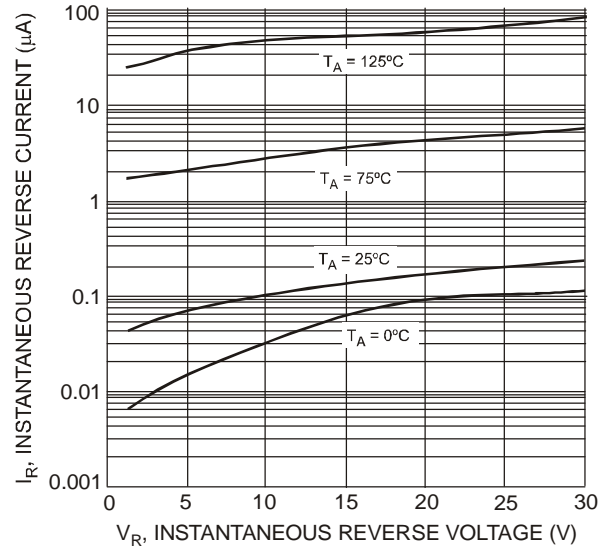


Fig. 2 Typical Reverse Characteristics

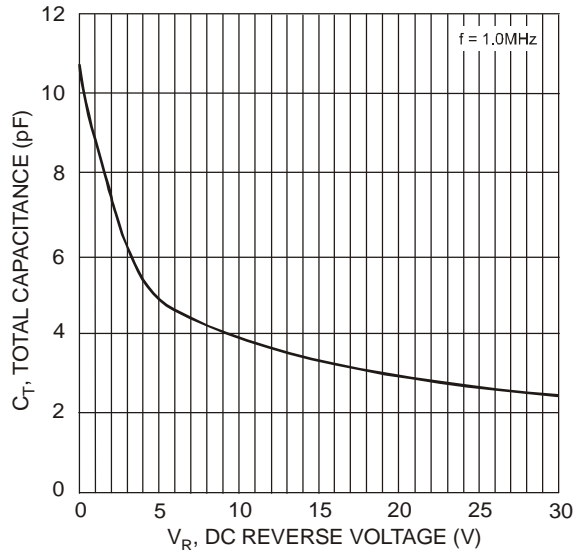


Fig. 3 Total Capacitance vs. Reverse Voltage

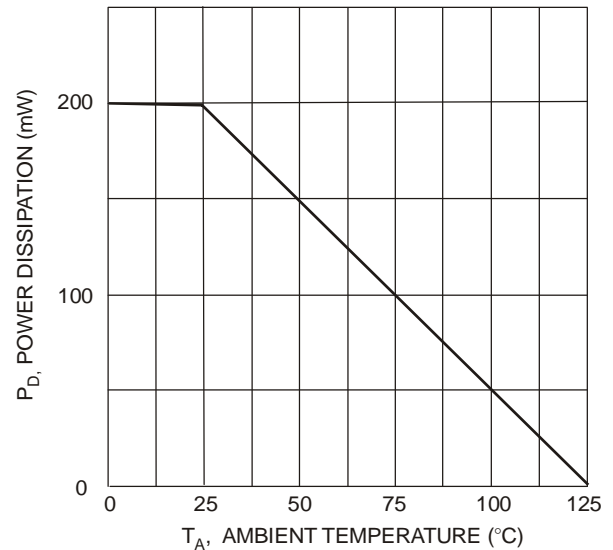


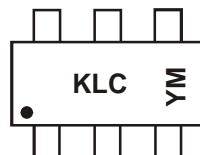
Fig. 4 Power Derating Curve

## Ordering Information (Note 6)

Part Number	Case	Packaging
BAT54JW-7-F	SOT-363	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

## Marking Information



KLC = Product Type Marking Code  
YM = Date Code Marking  
Y = Year (ex: N = 2002)  
M = Month (ex: 9 = September)

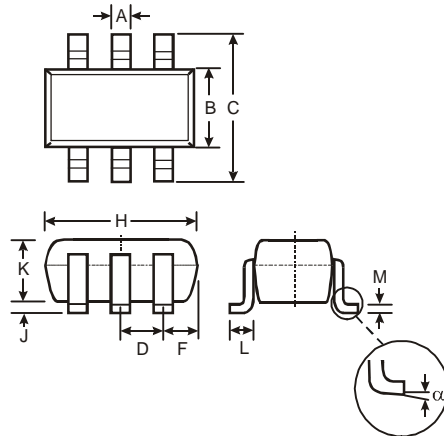
### Date Code Key

Year	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	M	N	P	R	S	T	U	V	W	X	Y	Z	A	B	C

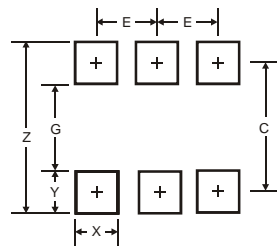
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

## Package Outline Dimensions



SOT-363		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Typ	
F	0.40	0.45
H	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.22
$\alpha$	0°	8°
All Dimensions in mm		

## Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C	1.9
E	0.65

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